



US00D404374S

United States Patent [19]
Kimura

[11] **Patent Number: Des. 404,374**

[45] **Date of Patent: **Jan. 19, 1999**

[54] **FIN FOR USE IN A SEMICONDUCTOR
WAFER HEAT PROCESSING APPARATUS**

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5,752,796 5/1998 Muka 414/935 X

[75] Inventor: **Norifumi Kimura**, Shiroyama-Machi,
Japan

Primary Examiner—Brian N. Vinson
Attorney, Agent, or Firm—Ladas & Parry

[73] Assignee: **Tokyo Electron Limited**, Tokyo-To,
Japan

[57] **CLAIM**

[**] Term: **14 Years**

I claim the ornamental design for a fin for use in a semi-
conductor wafer heat processing apparatus, as shown and
described.

[21] Appl. No.: **83,717**

DESCRIPTION

[22] Filed: **Feb. 12, 1998**

[30] **Foreign Application Priority Data**

Aug. 20, 1997 [JP] Japan 9-65104

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182, 144,
D13/144.1, 199, 179; 414/935-941, 217,
147; 437/247, 946

FIG. 1 a perspective view of fin for use in a semiconductor
wafer heat processing apparatus;
FIG. 2 a right side view thereof;
FIG. 3 a front elevational view thereof;
FIG. 4 a top plan view thereof;
FIG. 5 a bottom plan view thereof;
FIG. 6 a cross-sectional view taken along line VI—VI in
FIG. 3;
FIG. 7 a cross-sectional view taken along line VII—VII in
FIG. 3; and,
FIG. 8 a cross-sectional view taken along line VIII—VIII in
FIG. 3.

[56] **References Cited**

U.S. PATENT DOCUMENTS

4,857,689 8/1989 Lee 414/935 X

1 Claim, 1 Drawing Sheet

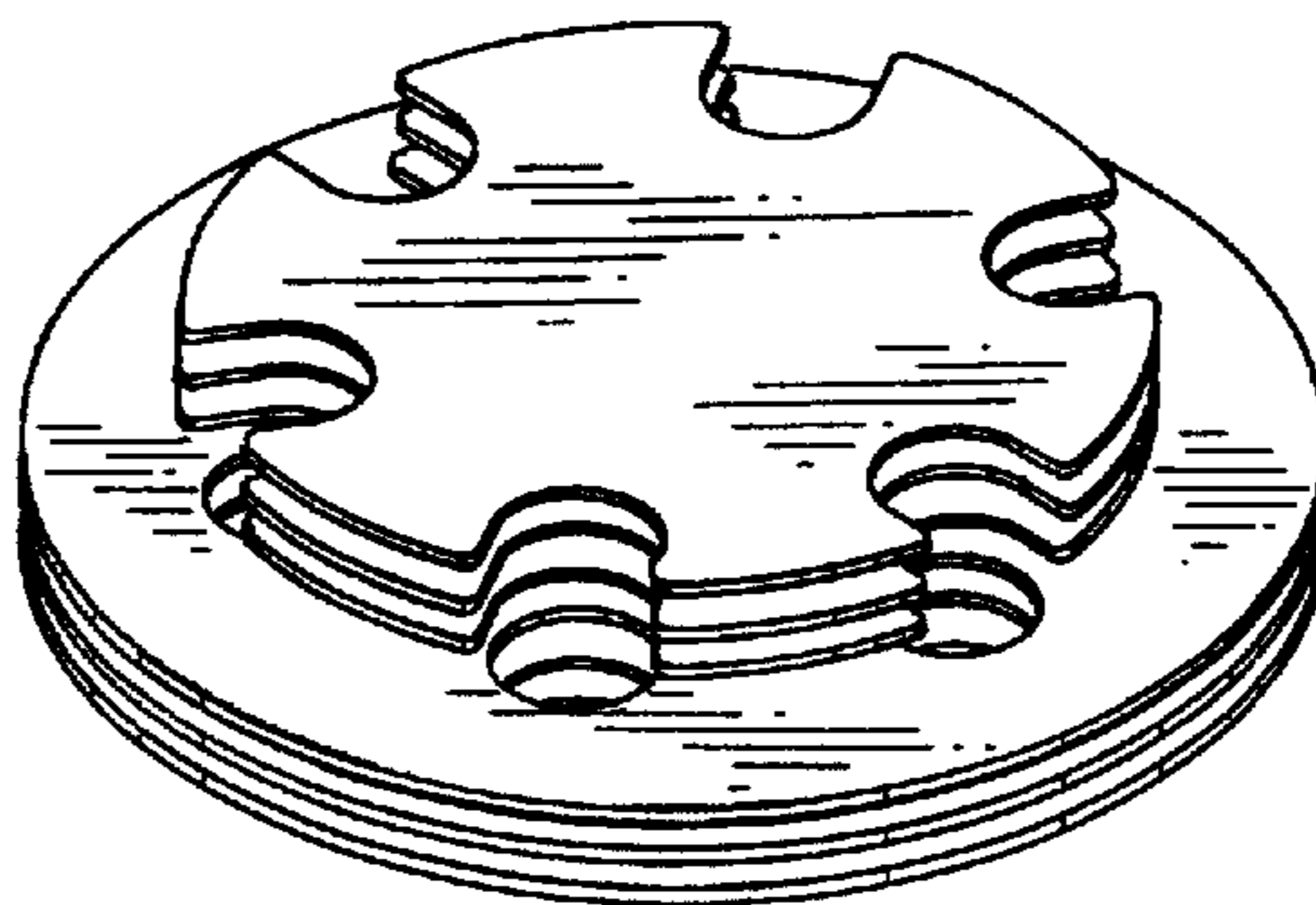


FIG. 1

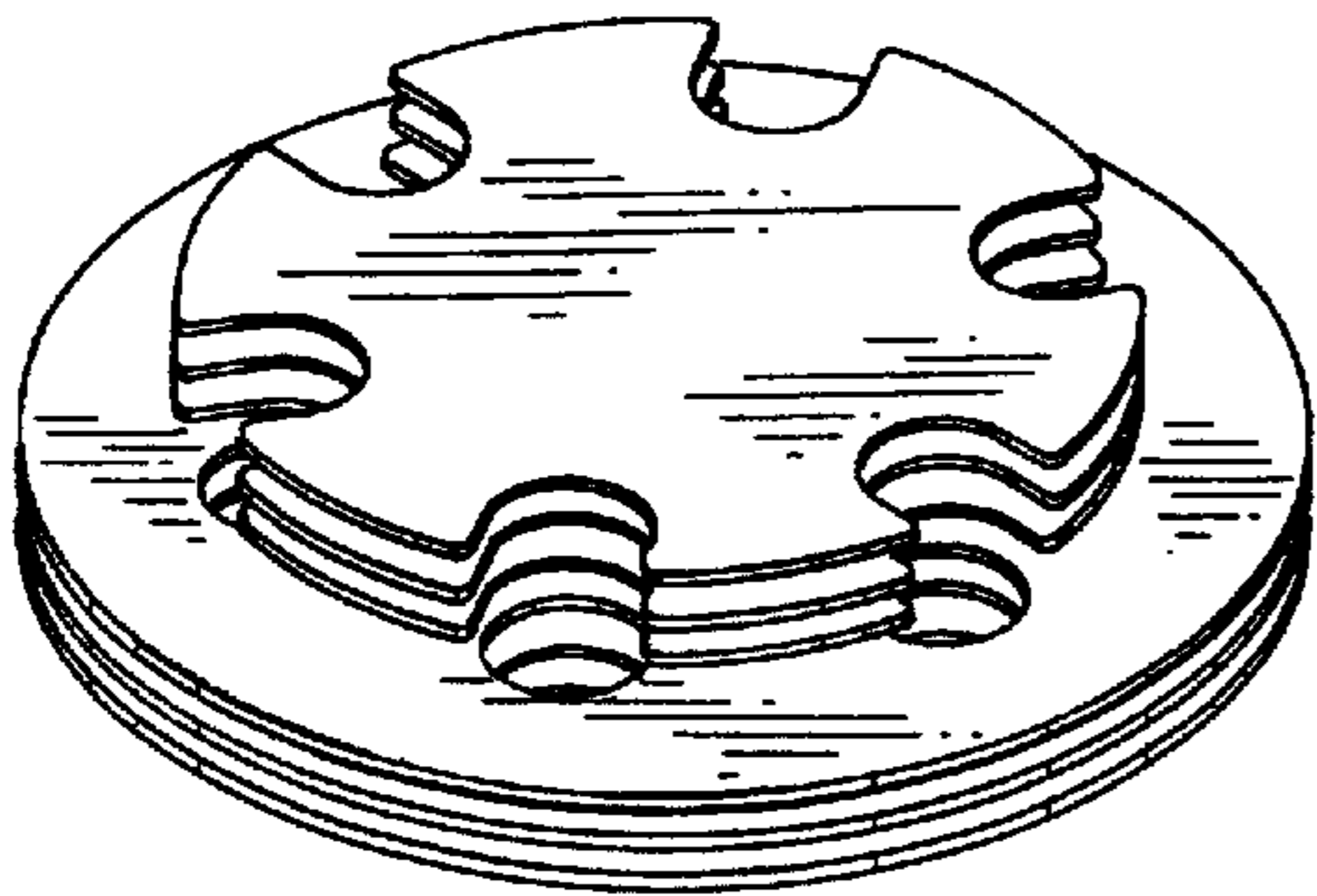


FIG. 2

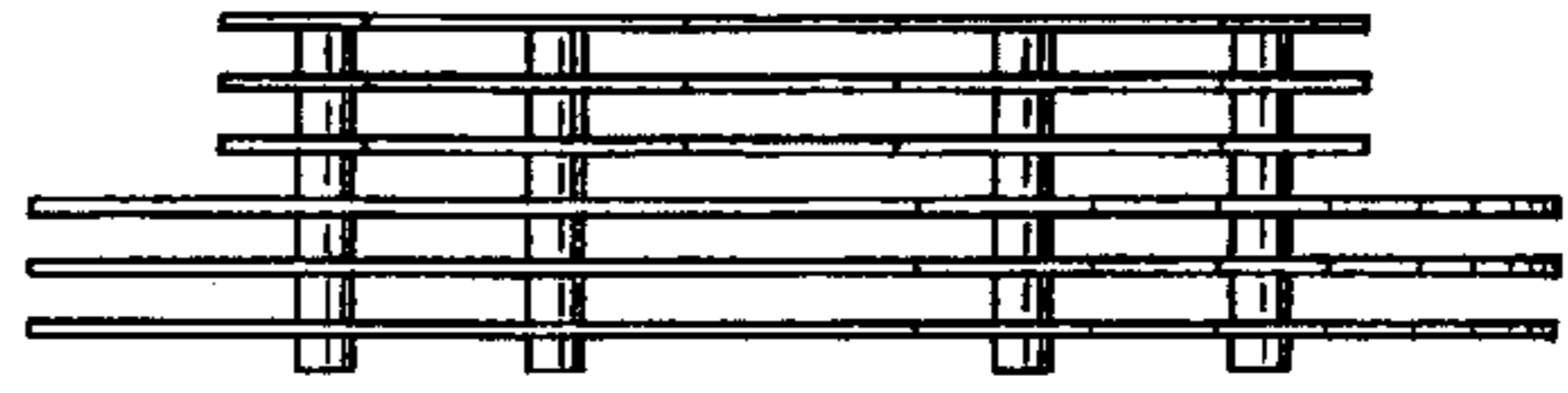


FIG. 3

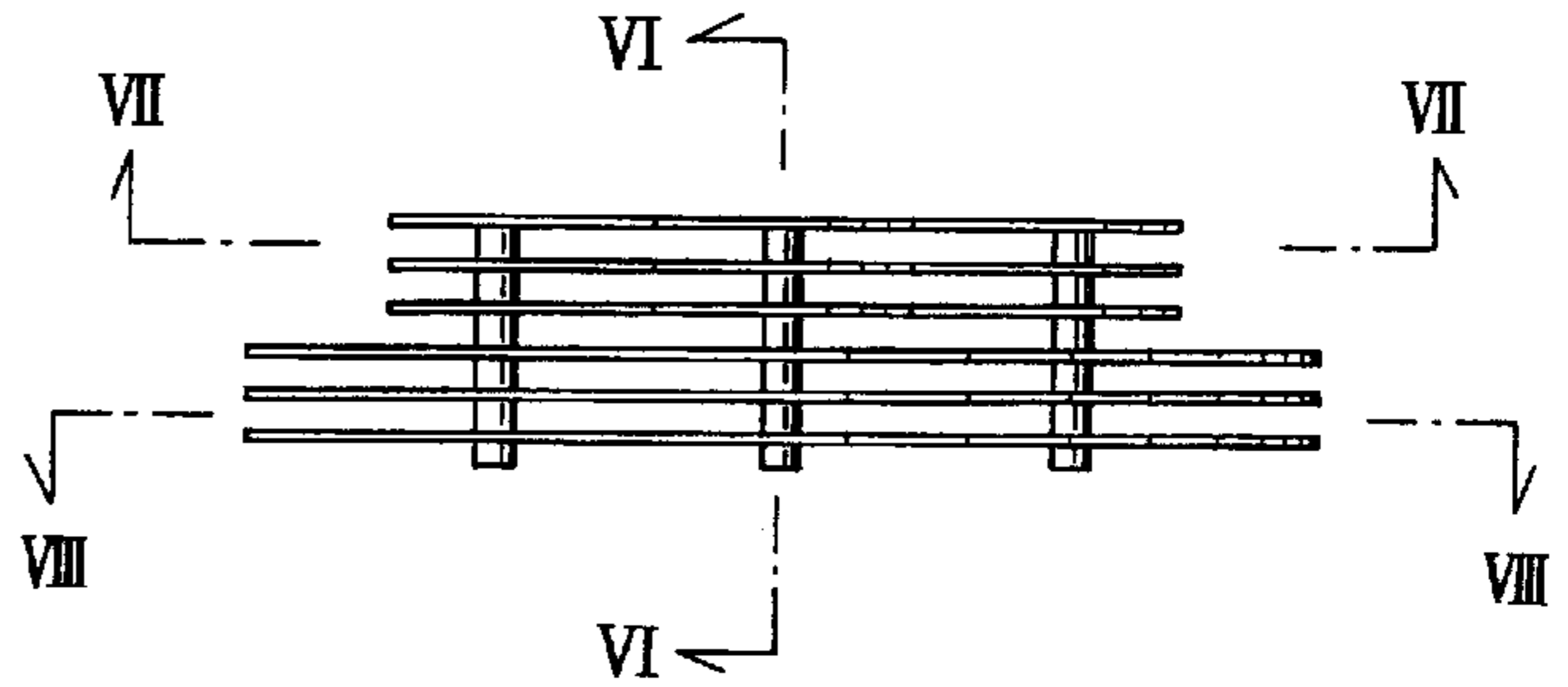


FIG. 4

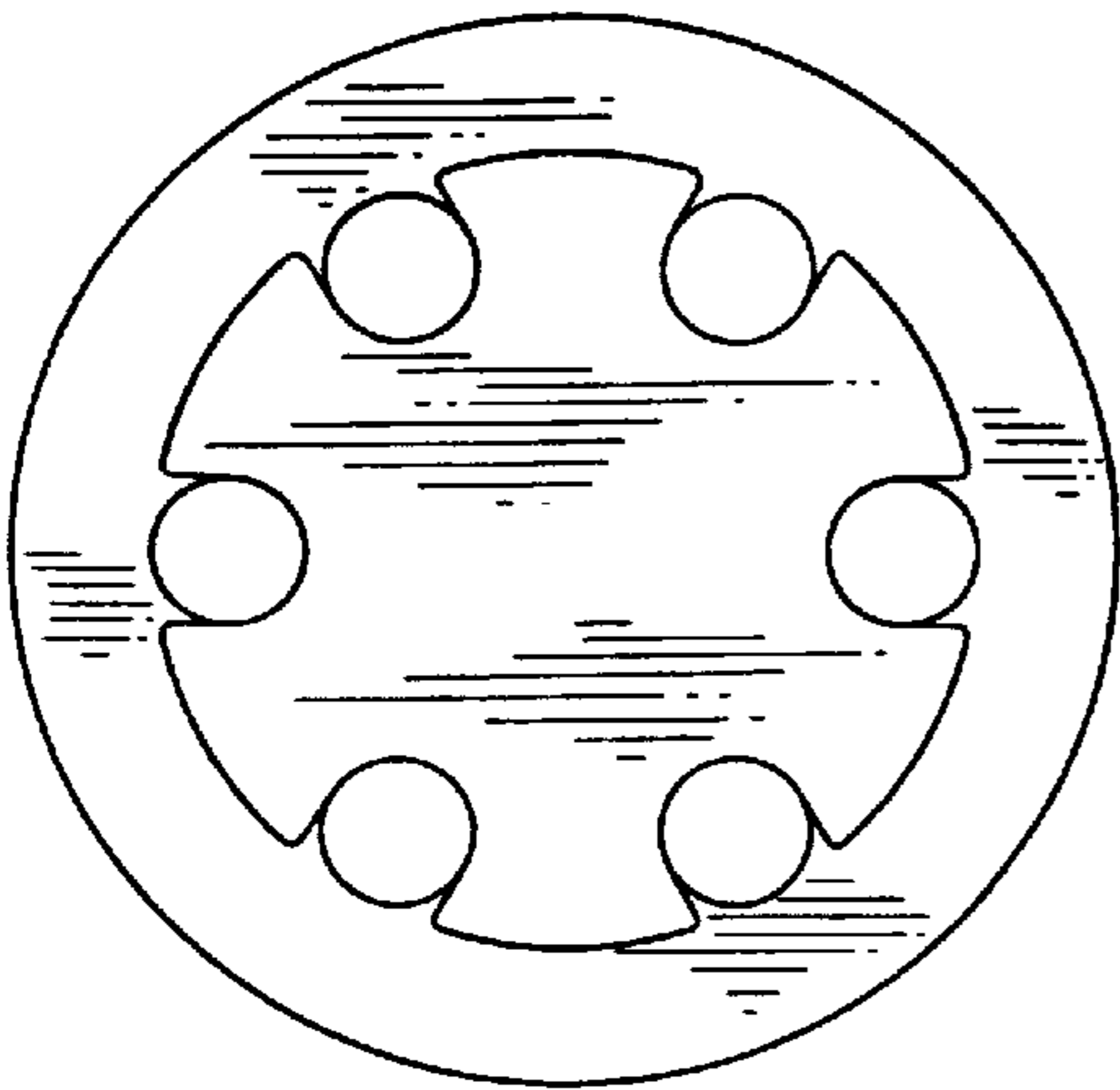


FIG. 7

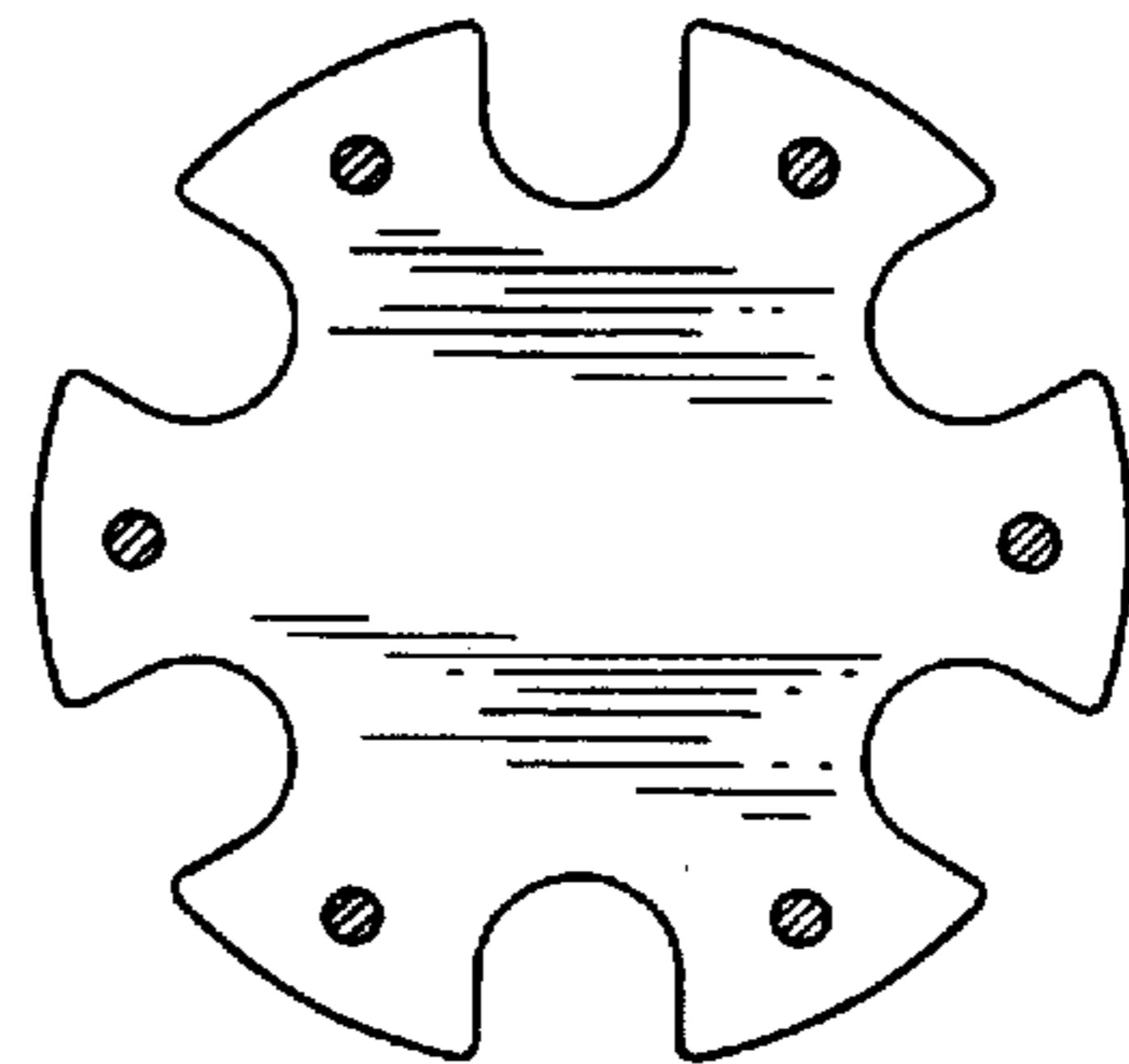


FIG. 5

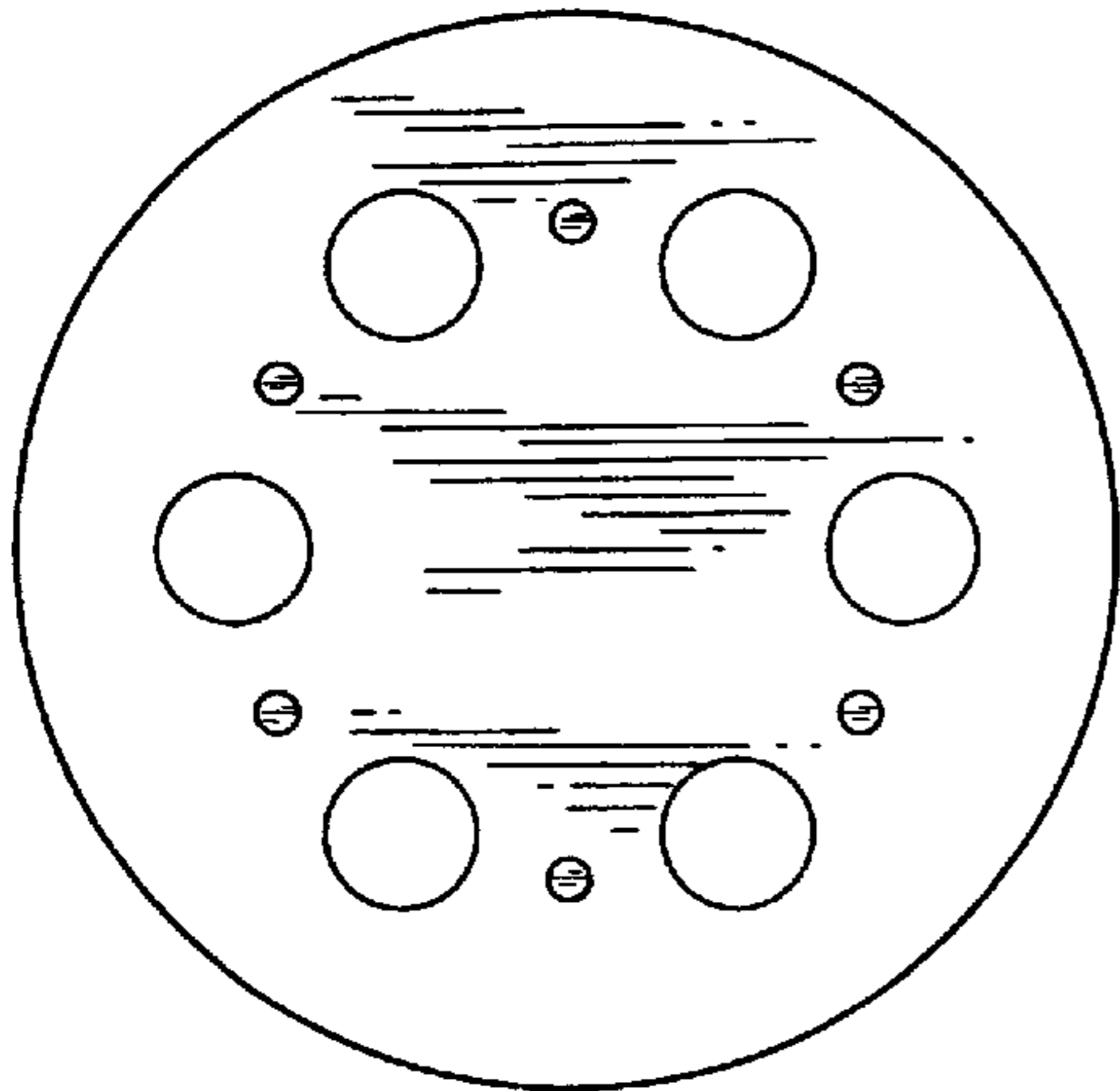


FIG. 8

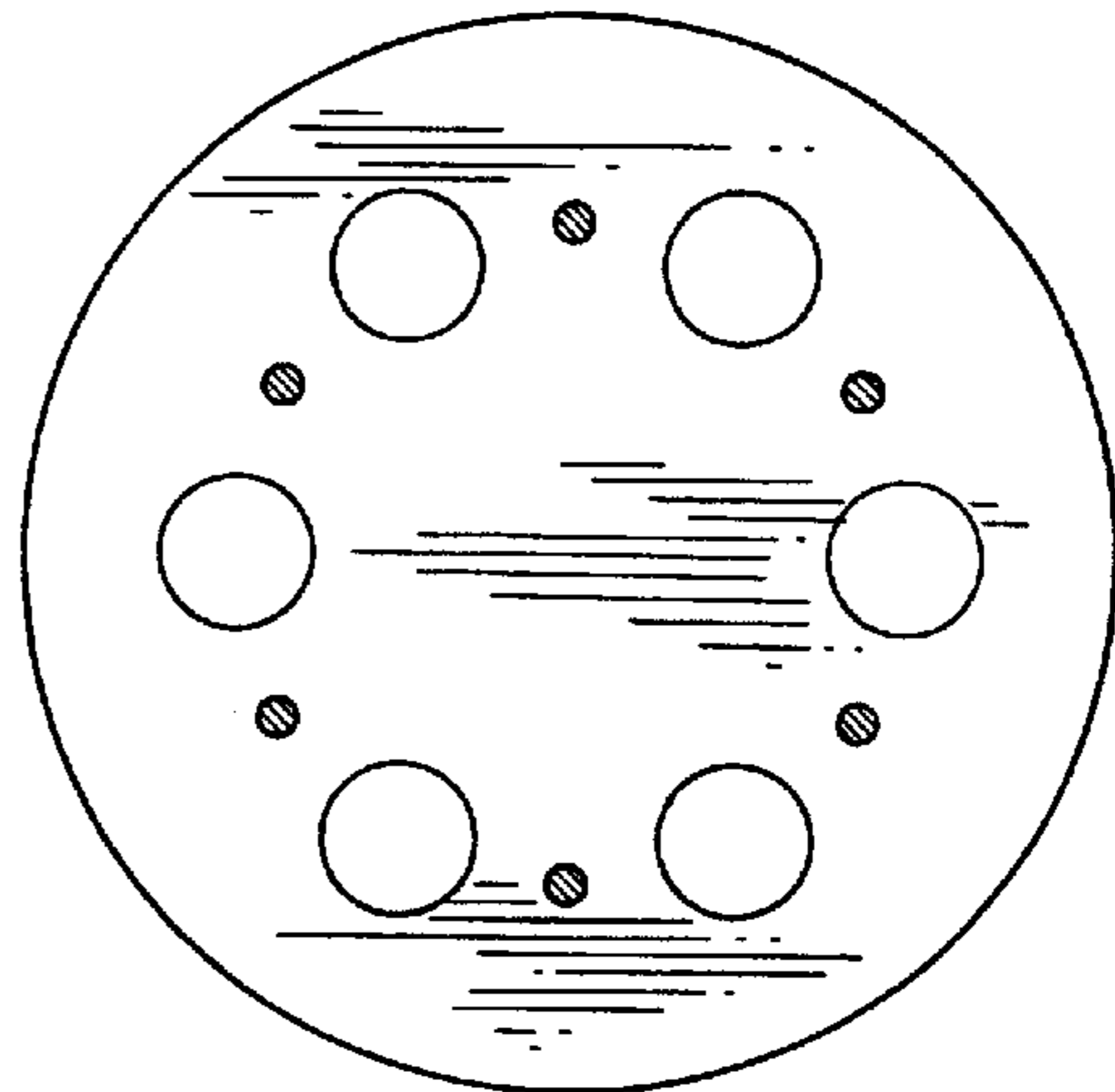


FIG. 6

